



ENGINEERING DEPT.	PRODUCT SPECIFICATION For CJ33 Series Board Mound Telephone Jack	SPEC.NO.: SPCJ065A
		PAGE: 1 / 3

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202 Methods for test of connectors for electronic equipment
MIL - STD - 1344 Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CJ3388*11SP

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: 1.6 mm (.063")

6.2 P.C. Board Layout: See attached drawings



REVIEWED : Eisley APPROVED : Eisley VERIFIED : Sandy .



ENGINEERING DEPT.	PRODUCT SPECIFICATION For CJ33 Series Board Mound Telephone Jack	SPEC.NO.: SPCJ065A
		PAGE: 2 / 3

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1.5 A Max 150 V AC (r.m.s.)
7.2	Contact Resistance	Open circuit of DC 20 mV max. 100 mA max. EIA-364-23B	Less than 20 mΩ Max. (Initial) Less than 30 mΩ Max. (Final)
7.3	Dielectric strength	Test between adjacent circuits of unmated connector. When applied AC 1000 V 1 minute between adjacent contacts. 1.5KVrms at 60Hz or 2250VDC, 1 minute between shield and contacts EIA-364-20B	No change
7.4	Insulation Resistance	When applied DC 500 V between adjacent terminal or ground EIA-364-21C	More than 500 MΩ Max. (Initial) More than 200 MΩ Max. (Final)

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact Normal force	Individually pin of contact area EIA-364-04A	0.1Kgf Min.
8.2	Durability	Connector shall be subjected to 750 cycles of insertion and withdrawal EIA-364-09C	Appearance: No damage Contact resistance Less than 30 mΩ Max.
8.3	Mating force	Measure force to mate samples at speed 25±3mm per minute with plug latch depressed EIA-364-13B	2 contacts: 1.6 Kgf Max. 4 contacts: 1.8 Kgf Max 6 contacts: 2.1 Kgf Max 8 contacts: 2.3 Kgf Max 10 contacts: 2.5 Kgf Max



ENGINEERING DEPT.	PRODUCT SPECIFICATION For CJ33 Series Board Mound Telephone Jack	SPEC.NO.: SPCJ065A
		PAGE: 3 / 3

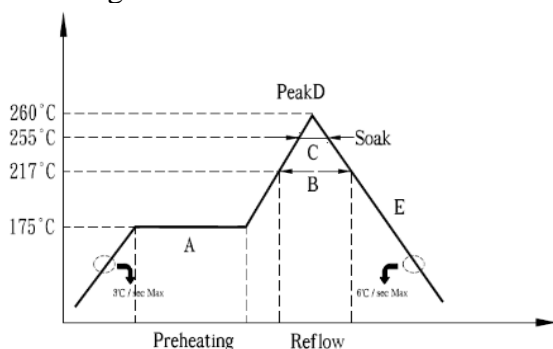
9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Humidity test	At a temperature of $40\pm 2^{\circ}\text{C}$ and relative humidity of 90-95% for 96 hours EIA-364-17B	Appearance: No damage Contact resistance Less than 30 m Ω Max.
9.2	Temperature Life	Exposing in a heat chamber at a temperature of $65\pm 2^{\circ}\text{C}$ for 96 hours EIA-364-17B	Appearance: No damage Contact resistance Less than 30 m Ω Max. Dielectric strength: To pass para 7-3
9.3	Salt spray	Temperature: $35\pm 2^{\circ}\text{C}$ Solution: $5\pm 1\%$ Spray time: 48 hours After test, rinse the sample with water and recondition the room temperature for 1 hour. EIA-364-26B	Appearance: No damage Contact resistance Less than 30 m Ω Max. Insulation resistance More than 200 M Ω Max.
9.4	Solder ability	Soldering time: 5 ± 0.5 second Soldering pot: $245\pm 5^{\circ}\text{C}$	Minimum: 95% of immersed area
9.5	Resistance to soldering heat	Refer Reflow temperature profile(11.1)	Appearance: No damage

10. OPERATING TEMPERATURE RANGE: -40 to $+85^{\circ}\text{C}$

11. Recommended IR Reflow Temperature Profile:

11.1 Using Lead-Free Solder Past



- A : Pre-Heating (175 \pm 25°,120 \pm 60 Sec.)
- B : Reflow (217°C,60~150 Sec)
- C : Soak (235°C \pm 5°C,24~36 Sec(30 \pm 20%))
- D : Max. Temp (260°C,10 Sec MAX)
- E : 6°C/sec Max